Bi-epitaxial template grain boundaries with different in-plane angles on (100) MgO substrates.

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Abstract

Using laser ablation CeO₂ and YBa₂Cu₃O_{7-d} layers have been deposited on (100) oriented MgO substrates for the creation of bi-epitaxial grain boundary weak links. X-Ray Diffraction measurements were used to measure the (in-plane) orientations of the layers. The CeO₂ layer has been structured using Ar ion beam etching or CaO lift off. Using these two structuring techniques it is possible to obtain two different grain boundary weak link angles: 18 and 27 degrees. Up till now only 45 degrees weak link angles have been reported in literature, using templates for the creation of these grain boundaries.

1. Introduction

In literature several ways create to bi-epitaxial Josephson junctions and dc SQUIDs grain boundaries have been described. Bicrystals of SrTiO₃ and Yttrium Stabilized ZrO₂ have been used [1,2] giving the possibility to vary the induced weak link angle between 0 and 45 degrees. The dependence of the critical current density on this angle is reported [1,2]. A second way for the creation of bi-epitaxial Josephson junctions makes use of different in-plane orientations of YBa2Cu3O7-d on top of structured multilayers [3-5]. The first reported bi-epitaxial template grain boundary junctions were obtained using (1102) Al₂O₃ substrates, an MgO template layer and a SrTiO₃ buffer layer [3]. An improvement of this technique was achieved using SrTiO₃ substrates, an MgO template layer and a CeO2 buffer layer [4]. All reported grain boundaries achieved in this way have an in-plane rotation of the YBa₂Cu₃O_{7-d} of 45 degrees between both sides of the grain boundary. A lower grain boundary angle has the advantage of higher critical currents and of lower expected noise.



Figure 1. Schematic of the template structure.

In this report we discuss the growth and orientation of CeO₂ and YBa₂Cu₃O_{7-d} on (100) oriented MgO substrates. To obtain a bi-epitaxial grain boundary weak link, the CeO₂ layer has to be structured (see figure 1). The effect of the structuring technique (Ar ion beam etching or CaO lift-off [6]) with respect to the orientation of the deposited YBa₂Cu₃O_{7-d} on MgO has been investigated. RBS measurements have been used to look for remainders of Ar and Ca, due to the structuring of the CeO₂ template layer.

2. Experimental

All layers have been deposited by laser ablation. Deposition of $YBa_2Cu_3O_{7-d}$ took place using a polycrystalline $YBa_2Cu_3O_x$ target. The CeO_2 was deposited using an amorphous/polycrystalline CeO_2 target. The CaO was deposited using a polycrystalline CaO target. The deposition of the $YBa_2Cu_3O_{7-d}$ and the CeO_2 took place at elevated

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temperatures, CaO was deposited at room temperature.

The orientation of the layers perpendicular and parallel to the substrate surface was checked using (P)XRD.

Structuring of the CeO₂ layer took place by Ar ion beam etching under an angle of 40 degrees with the substrate surface (Kauffmann source, beam voltage 500 volt, beam current 10 mA) or using the CaO lift-off technique.

3. Results

3.1. Orientation

Using (100) oriented MgO substrates and a CeO₂ template layer it is possible to create an in-plane rotation of YBa₂Cu₃O_{7-d} on CeO₂ on MgO with respect to YBa₂Cu₃O_{7-d} deposited directly on MgO. On the MgO substrates CeO₂, YBa₂Cu₃O_{7-d} and YBa₂Cu₃O_{7-d}/CeO₂ layers have been deposited. Powder X-Ray Diffraction measurements have been performed on these layers to look for their orientations

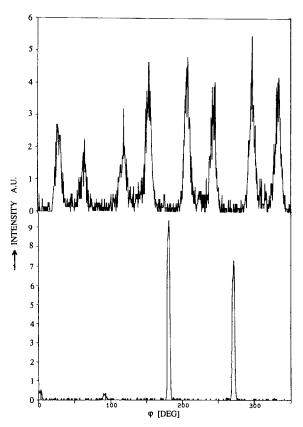


Figure 2. Phi scan of a CeO₂ layer on a MgO substrate. Shown are the (204) MgO reflection (bottom) and the (113) CeO₂ reflection (top).

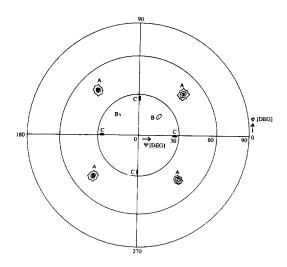


Figure 3. Pole diagram of YBa₂Cu₃O_{7-d} on Ar ion beam etched MgO. A=(206) YBa₂Cu₃O_{7-d}, B=(108) YBa₂Cu₃O_{7-d}, C=(204) MgO.

perpendicular to the substrate.

CeO₂ layers deposited at deposition temperatures T_{dep} between 700 and 750°C, an oxygen pressure P_{O2} of 20 Pa, a laser fluence I of 2.0 J/cm² and a target-substrate distance d of 35 mm, show 95% (h00) and 5% (hhh) oriented material. In figure 2 a phiscan of a 100 nm thick CeO₂ layer (T_{dep} = 700 °C) on top of an MgO substrate is given. The (113) CeO₂ reflection is shown in the upper part of the figure 2, whereas in the lower part the (204) reflection of the MgO substrate is given. The in-plane direction of the CeO₂ layer is \pm 18 degrees rotated with respect to the cubic to cubic orientation as mentioned in literature [4,5].

The CeO₂ layer is structured using two different techniques: Ar ion beam etching and CaO lift-off. By structuring the CeO₂ layer with Ar ions, also the toplayer of the MgO substrate is etched. Using the CaO lift-off technique the MgO substrate is for a period of about 10 minutes in contact with distilled water, possibly causing some damage to the MgO surface.

YBa₂Cu₃O_{7-d} layers have been deposited on two differently treated MgO substrates. The first substrate has been etched for 80 seconds using Ar ions. On the second MgO substrate a CaO layer has been deposited at room temperature, followed by a heat treatment at 700 °C for 10 minutes, representing the heat treatment for CeO₂ deposition. Finally the CaO has been removed by putting the substrate into an ultrasonic bath with distilled water for ten minutes. YBa₂Cu₃O_{7-d} layers which have been grown on top of these substrates show c-axis

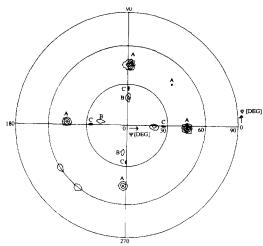


Figure 4. Pole diagram of YBa₂Cu₃O_{7-d} on MgO after CaO lift-off. A=(206) YBa₂Cu₃O_{7-d}, B=(108) YBa₂Cu₃O_{7-d}, C=(204) MgO.

orientation. In figure 3 the pole figure of the (206)/(108) YBa₂Cu₃O_{7-d} and the (204) MgO reflections are given for the first substrate. It can be seen that the [110] direction of YBa₂Cu₃O_{7-d} is parallel to the [100] direction of the MgO. No other in-plane orientations are found (see also [7]). The in-plane orientation of the YBa₂Cu₃O_{7-d} layer on the second MgO substrate is [100] YBa₂Cu₃O_{7-d} parallel to [100] MgO as can be seen in figure 4. The unmarked reflections can be explained by (110) oriented YBa₂Cu₃O_{7-d} as observed by PXRD.

The CaO lift-off procedure doesn't effect the critical temperature of the YBa₂Cu₃O_{7-d} layer on top of the MgO substrate.

YBa₂Cu₃O_{7-d} grown on top of a CeO₂ layer on a MgO substrate has the c-axis perpendicular to the substrate surface. The in-plane orientation of this layer on CeO₂ is 45 degrees rotated with respect to the cubic to cubic orientation as reported by Char et al. [4].

The resulting grain boundary angle of the structure of figure 1 will be 18 degrees if the CeO₂ is Ar ion beam etched, and 27 degrees if the CaO lift-off technique is used.

3.2, RBS

In figure 5 part of the random RBS spectrum of substrate one is given. At an energy of 1.25 MeV an extra amount of backscattered He ions (FWHM=37 keV; the FWHM for a monolayer Au on SiO₂ on Si is 17 keV with the settings used in this experiment.) is visible which is not visible in RBS spectra of

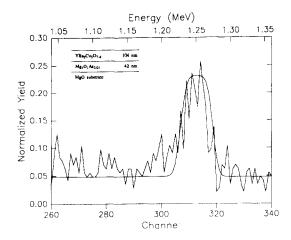


Figure 5. Part of the RBS spectrum of substrate one. Shown are the measurements and a simulation of a model (see inset).

YBa₂Cu₃O_{7-d} layers on non Ar etched MgO. The extra peak can not be explained by Ar atoms just at the interface of the MgO and the YBa₂Cu₃O_{7-d} because of its FWHM value. It can be explained by taking a substrate toplayer of 42 nm with the nominal composition Mg:O:Ar = 1:1:0.01 into account (see inset of figure 5). Because the accelerator voltage of the Ar ions is only 500 volt during etching the Ar ions will not penetrate 42 nm into the MgO substrate. Due to the heat treatment caused by the deposition of YBa₂Cu₃O_{7-d} on the Ar etched substrate, probably diffusion of the Ar ions into the substrate has taken place.

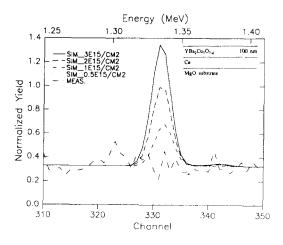


Figure 6. Part of the RBS spectrum of substrate two. Shown are the measurement and simulations of a model (see inset) with different Ca densities.

In figure 6 part of the random RBS spectrum of the second sample is given. To increase the sensitivity the angle between the incoming He⁺ ions and the detector has been increased to 60° resulting in a FWHM value of 17 keV for the same monolayer gold as mentioned above. Apart from the measurement also simulations of different Ca densities at the MgO surface are given. It can be seen that the upper limit of Ca near the MgO surface equals 1·10¹⁵ atoms/cm². This means that at maximum one Ca atom per MgO unit cell surface area is present.

3.3. dc SQUIDs

Using the layers and applying the structuring techniques as described above, washer type dc SQUIDs have been structured in the YBa₂Cu₃O_{7-d} layers using Ar ion beam etching.

Voltage modulation up to 79 K has been observed. At 77 K the maximum voltage modulation was 1.5 μ V. The highest modulation voltage we have observed was 90 μ V at 4.2 K, with a flux to voltage transfer $\partial V/\partial \varphi = 310 \ \mu V/\varphi_0$. More details of the electrical measurements will be published elsewhere [9].

4. Summary

Using a CeO₂ template layer on MgO substrates it is possible to create bi-epitaxial grain boundary weak links in the YBa₂Cu₃O_{7-d} layer on top of this structure. If the CeO₂ is structured using Ar ion beam etching an angle of 18 degrees results. CaO

lift-off results in a weak link angle of 27 degrees. Washer type dc SQUIDs structured in the YBa₂Cu₃O_{7-d} (CeO₂ etching took place using Ar ion beam etching) show voltage modulation up to 79 K.

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